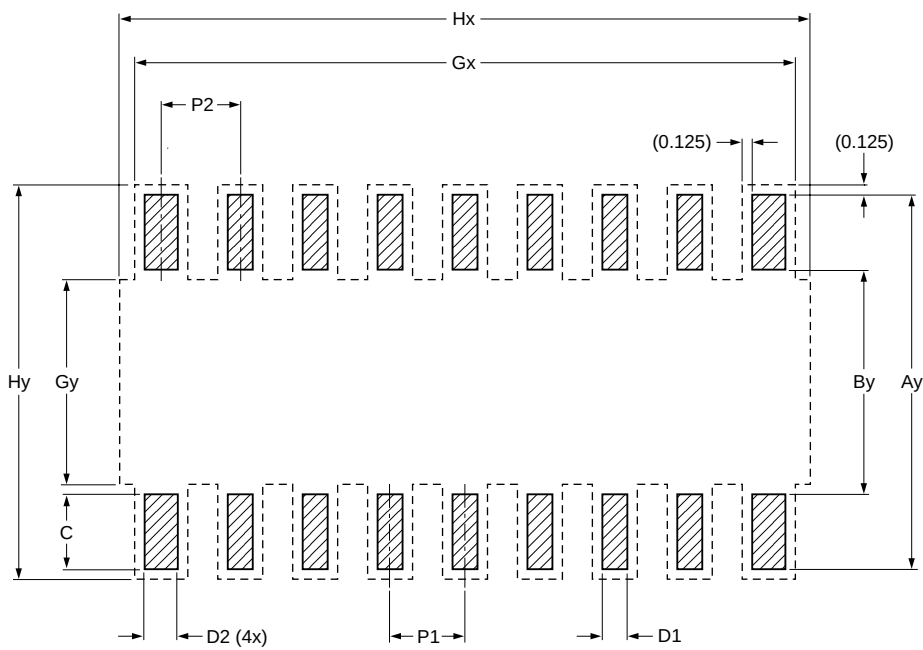


Footprint information for reflow soldering of TSSOP64 package

SOT646-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
 occupied area

DIMENSIONS in mm

| P1    | P2    | Ay    | By    | C     | D1    | D2    | Gx     | Gy    | Hx     | Hy    |
|-------|-------|-------|-------|-------|-------|-------|--------|-------|--------|-------|
| 0.500 | 0.560 | 8.900 | 6.100 | 1.400 | 0.280 | 0.400 | 16.270 | 7.000 | 17.900 | 9.150 |